

REMARKS

Original claims 1-46 have been canceled, and new claims 47-67 have been added. The new claims are directed to a semiconductor component.

As shown in Figure 2B, the component 50 includes a semiconductor die 54 having die contacts 62, such as bond pads, and an electrically insulating die passivation layer 76. The component 50 also includes a plurality of redistribution conductors 66 on the die passivation layer 76 configured to redistribute the pattern of the die contacts 62 into an area array, such as a grid array. In addition, the redistribution conductors 66 can either "fan out" or "fan in" the pattern of the die contact 62.

The component 50 also includes an electrically insulating outer passivation layer 78 having openings 82 aligned with selected portions of the conductors 76. The openings 82, and the selected portions of the conductors 76, are arranged in the area array provided by the redistribution conductors 66. The component 50 also includes a plurality of bumped contacts 58 in the openings 82 in the outer passivation layer 78 bonded to the selected portions of the redistribution conductors 66.

The component 50 can also include under bump metallization layers 44 (Figure 1B) configured to facilitate bonding of the bumped contacts 58 to the redistribution conductors 66. In addition, the component 50 can include test contacts 60 comprising selected portions of the redistribution conductors 66 aligned with second openings 80 in the outer passivation layer 78.

Favorable consideration and allowance of claims 47-67 is respectfully requested. An Information Disclosure Statement is being filed concurrently with this Preliminary

Amendment. Should any issues arise that will advance this case to allowance, the Examiner is asked to contact the undersigned by telephone.

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Respectfully submitted:



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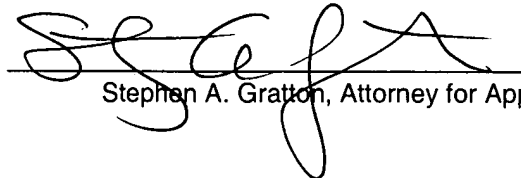
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